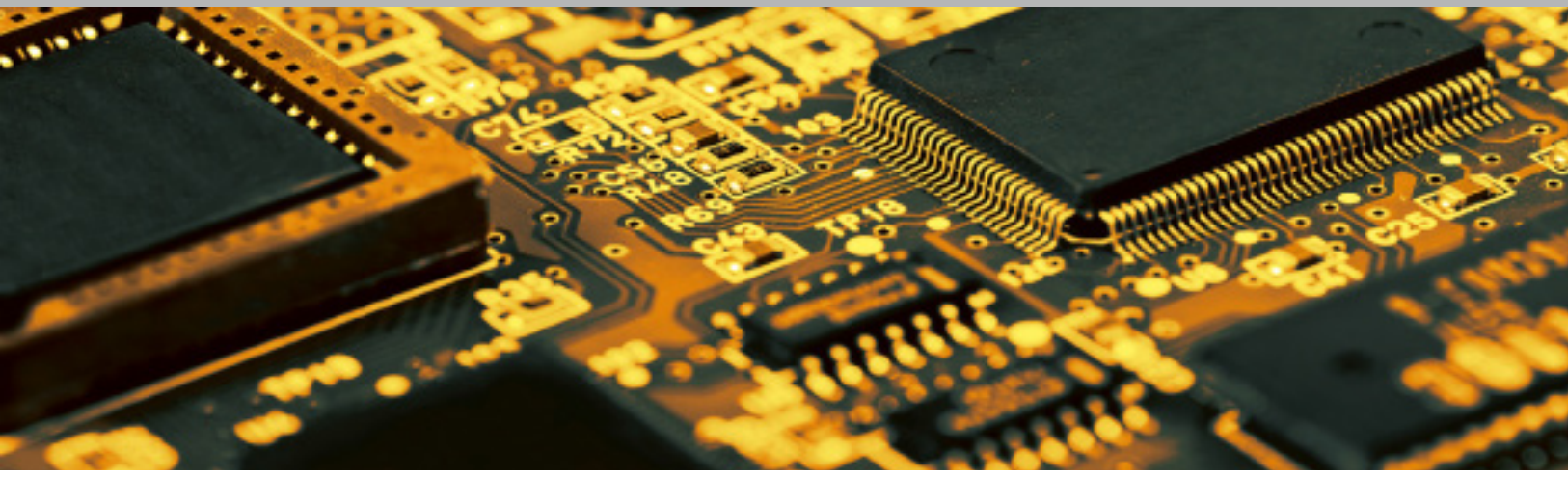
MIRTEC

3D AOI Series

MV-3 OMNI MARK-II



- 15 Megapixel Top Camera
- 12 Projection Moiré Technology
- 8 Phase Coaxial Color Light
- 18 Megapixel Angled Camera
- 45mm Tall Parts Inspection (Option)
- Extended Top(70㎜)/Bottom(100㎜) Clearance

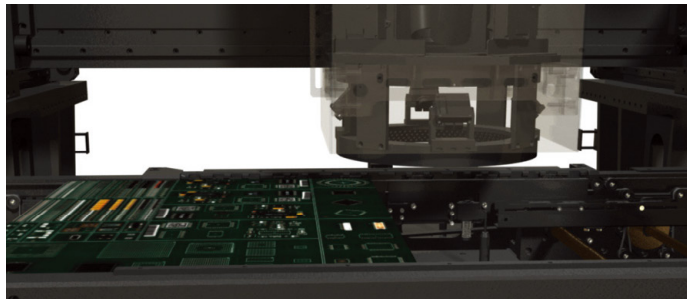
3D AOI Series

MV-3 OMNI MARK-II

MV-3 OMNI MARK-II Series is a Full-3D benchtop vision inspector with 15 Megapixel high-resolution camera, Digital Moiré 12 projection, 18 Megapixel side camera, and 8 phase coaxial color lighting. It is capable of inspecting 03015(mm) chips and features a Z-axis for inspecting tall components up to 45mm.

Design for Space Utilization

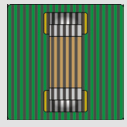
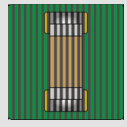
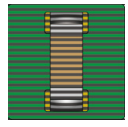
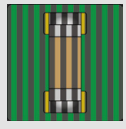
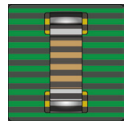
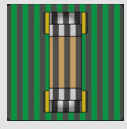
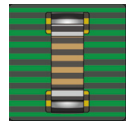
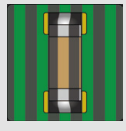
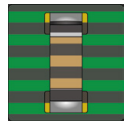
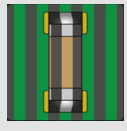
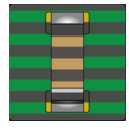
MV-3 OMNI MARK-II is an benchtop machine that is free from line configuration, making it is easy to arrange the machine and handle material easily. It is a universal system that demonstrates excellent ability even in small quantity production of various kinds without being influenced by the narrowness of manufacturing facilities and frequent inspection material alteration.

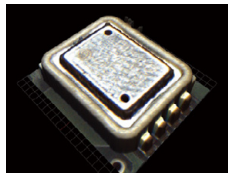
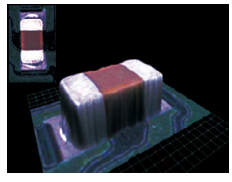
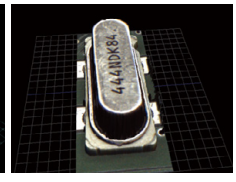


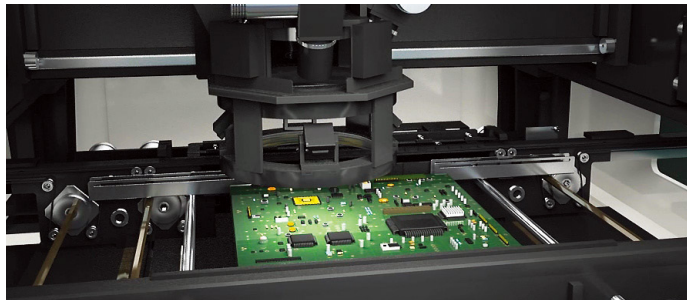
Digital 12 Projection Moiré Technology

Moiré Projection Unit measures a component in EWSN 4 directions to obtain 3D image for failsafe and high-speed defect detection.

- Obtain 3D image without blind spots using 4(four) 3D projections
- Various component height inspection with the combination of high, medium and low frequency moiré pattern
- Linkage with the main camera to apply Full 3D inspection to detect various defects flawlessly

Frequency	1. Projector	2. Projector	3. Projector	4. Projector
High				
Medium				
Low				



High Resolution 15 Megapixel Camera

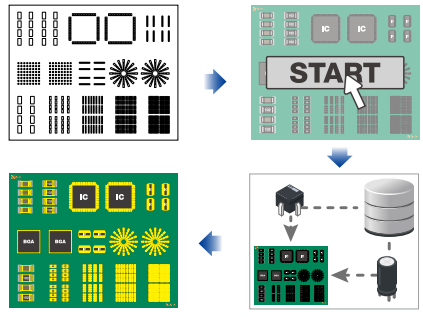
We are proud to have applied the next generation vision system with the 15 Megapixel high resolution camera for more precise and stable inspection and high speed CoaXPress transmission method to allow 4 times more data transmission and 40% increased process speed.

- 15 Megapixel Camera Loaded
- CoaXPress high performance vision system applied
- Large FOV to increase inspection speed
- Processing speed increased by 40% compared to Camera Link

Deep Learning applied Auto Teaching Tool

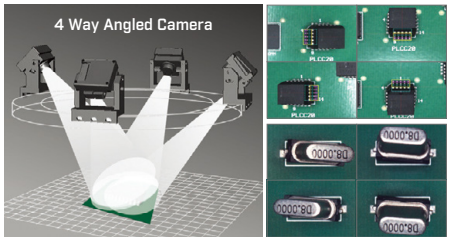
Inspection software which is applied Deep Learning solution search the most suitable component information and teach the component automatically. User would have the best inspection quality always regardless of user's skill as all of process will be done by a few clicks.

- Reduce teaching time more over 90% than manual teaching
- Secure the best inspection quality always by inspection quality and working process standardization
- Accurate component searching and matching by applying Deep Learning solution



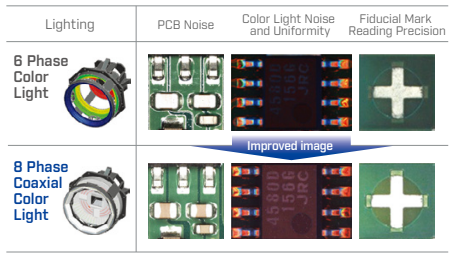
18 Megapixel Angled Camera

· 4 cameras in EWSN applied
· The only solution for J-lead, QFN and Coil Solder inspection
· Full-PCB inspection with side cameras



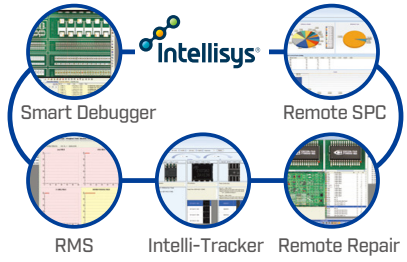
8 Phase Coaxial Color Light

· Color change extraction following angle of reflection
· Ideal for Chip / IC lift, micro crack and solder inspection
· Precise solder joint inspection



Intellisys® System

Possible to recognize in advance when a defect occurs in the line and support to reduce cost due to defects by remote controlling.



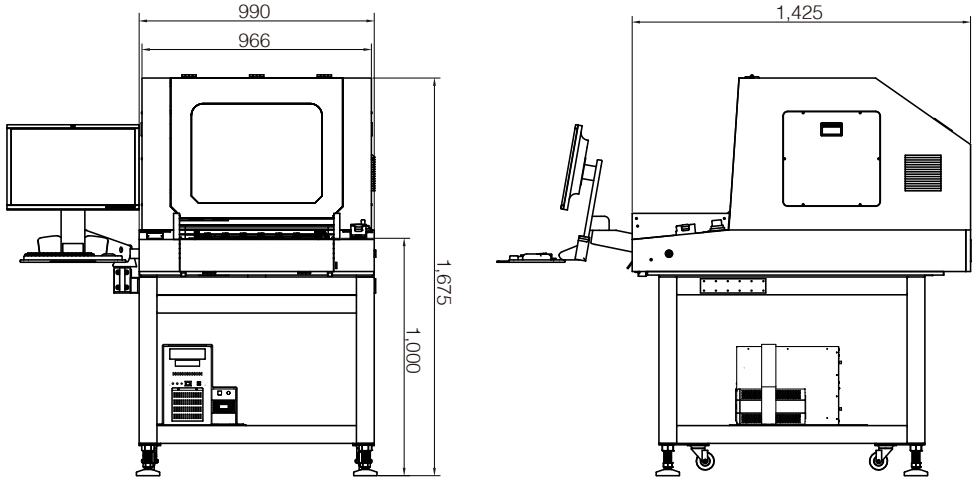
Specifications

Model			MV-3 OMNI MARK-II
PCB Size Range			
Benchtop AOI			50 x 50 ~ 480 x 400 mm
OMNI-VISION® 3D / 2D Inspection Technology			
3D Inspection Technology			Digital 12 Projection Moiré Technology
Height Accuracy			±3 μm
3D / 2D Maximum Inspection Speed			
15 Megapixel Camera	CoaXPress	10 μm	2,010 mm^2 / Sec
		15 μm	4,550 mm^2 / Sec
2D Maximum Inspection Speed			
15 Megapixel Camera	CoaXPress	10 μm	5,080 mm^2 / Sec
		15 μm	10,716 mm^2 / Sec
System Specification			
Lighting System			8 Phase Coaxial Color Lighting System
Multi-Vision System (Side Camera)		Option	18/10 Megapixel Digital Color Side Camera (4ea)
Software		Standard	Built-in SPC, Built-in Repair
		Option	TRMS, RRS, OLTT, RDS, Remote SPC, ePM-AI²/Siemens Valor
PCB Clearance		Top	45 mm (Option : 70mm)
		Bottom	100 mm
PCB Thickness			0.5 mm ~ 3 mm
Maximum PCB Weight			3 kg
Minimum Measurement Size		10 μm	03015 Chip (mm) / 0.3 Pitch (mm)
		15 μm	0603 Chip (mm) / 0201 Chip (inch) / 0.4 Pitch (mm)
Robot Positioning System		X/Y Axis	Servo Motor System
Power Requirements			Single Phase(s) 200-240V 50-60Hz, 1.1 kW
Dimension and Weight			
Dimension			990(W) x 1,425(D) x 1,675(H) mm
Weight			Approx. 550 kg

※ We will not be responsible for any problems caused by using unverified BARCODE READER. Contact our HQ for the list of allowed BARCODE READER models to use.

Dimension

(Unit : mm)



• Data subject to change without notice.

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